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## FACSIMILE COVER SHEET

<b>Date:</b>	<b>January 6, 2006</b>	<b>Fax:</b>	<b>571-273-8300</b>
<b>To:</b>	<b>U.S. Patent and Trademark Office</b>	<b>Phone:</b>	
<b>Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450</b>			
<b>From:</b>	<b>David C. Hsia</b>		
<b>Serial No.:</b>	<b>10/826,800</b>		
<b>Docket:</b>	<b>10030280-4</b>		
<b>Re:</b>	<b>Restriction Requirement</b>		
<b>Pages:</b>	<b>6 (including cover sheet)</b>		

### Message:

Re: Applicant(s): Tanya J. Snyder, Robert H. Yi, Robert E. Wilson  
Assignee: Agilent Technologies, Inc.  
Title: Wafer Bonding Using Reactive Foils for Massively Parallel  
Micro-Electromechanical Systems Packaging  
Serial No.: 10/826,800  
Examiner: David Nhu  
Docket No.: 10030280-4  
Filed: April 15, 2004  
Group Art Unit: 2818

Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

- (1) Transmittal Letter (1 page);
- (2) Response to Office Action (4 pages).

The information contained in this message is intended only for the personal and confidential use of the designated recipient(s) named above. This message may be an attorney-client communication and may be protected by the work product doctrine. As such, this document is privileged and confidential. If the reader of this message is not the intended recipient, you are hereby notified that you have received this document in error and that any review, dissemination, distribution, or copying of this message is strictly prohibited. If you have received this communication in error, please notify us immediately by telephone and destroy any copies of this document in your possession. Thank you.

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AVAGO TECHNOLOGIES, LTD.  
P.O. Box 1920  
Denver, Colorado 80201-1920

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ATTORNEY DOCKET NO. 10030280-4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Tanya J. Snyder et al.

Serial No.: 10/826,800

Examiner: David Nhu

Filing Date: April 15, 2004

Group Art Unit: 2818

Title: WAFER BONDING USING REACTIVE FOILS FOR MASSIVELY PARALLEL  
MICRO-ELECTROMECHANICAL SYSTEMS PACKAGING

COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- ☒ Response/Amendment ☐ Petition to extend time to respond  
☐ New fee as calculated below ☐ Supplemental Declaration  
☒ No additional fee (Address envelope to "Mail Stop Amendments")  
☐ Other: (Fee \$ )

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	6	MINUS	20	= 0	X 50	\$ 0
INDEP. CLAIMS	2	MINUS	3	= 0	X 200	\$ 0
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ 360	\$ 0
EXTENSION FEE	1 <sup>ST</sup> MONTH 120.00 <input type="checkbox"/>	2 <sup>ND</sup> MONTH 450.00 <input type="checkbox"/>	3 <sup>RD</sup> MONTH 1020.00 <input type="checkbox"/>	4 <sup>TH</sup> MONTH 1590.00 <input type="checkbox"/>	OTHER FEES	
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 50-3718. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 50-3718 pursuant to 37 CFR 1.2 5. Additionally please charge any fees to Deposit Account 50-3718 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this transmittal letter is enclosed.

Respectfully submitted,

Tanya J. Snyder et al.

By

David C. Hsia  
Attorney/Agent for Applicant(s)

I hereby certify that this paper is being facsimile transmitted to the Patent and Trademark Office on the date shown below:

Date of facsimile: January 6, 2006

Typed Name: David C. Hsia

Signature: 

Reg. No. 46,235

Date: January 6, 2006

Telephone No. (408) 382-0480

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Tanya J. Snyder, Robert H. Yi, Robert E. Wilson  
Assignee: Agilent Technologies, Inc.  
Title: Wafer Bonding Using Reactive Foils for Massively Parallel Micro-Electromechanical Systems Packaging  
Serial No.: 10/826,800 Filing Date: April 15, 2004  
Examiner: David Nhu Group Art Unit: 2818  
Docket No.: 10030280-4

San Jose, California  
January 6, 2006

Mail Stop Amendment  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the December 8, 2005 Office Action, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.

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